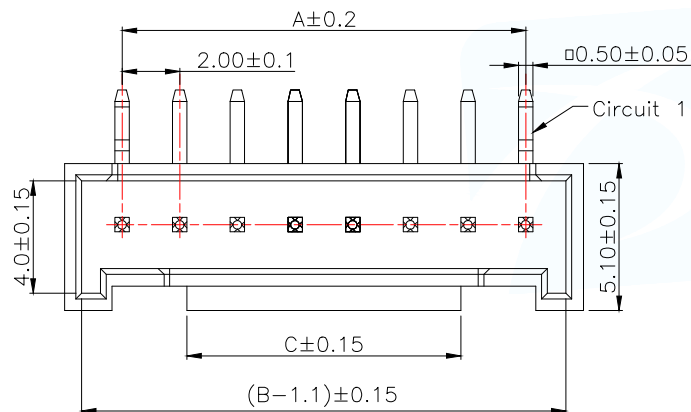
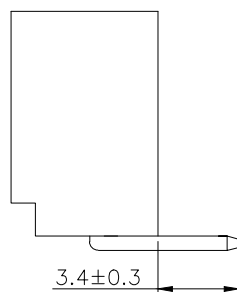
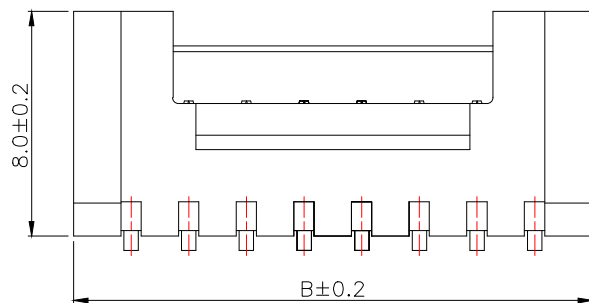
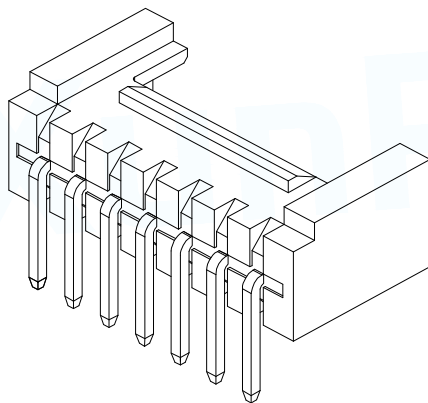


SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10\text{m}\Omega$
4. 绝缘电阻: $\geq 100\text{M}\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求。

Part No	Pin	A	B	C
WAFER-HY2.0-2PWZ	2	2.00	6.00	3.00
WAFER-HY2.0-3PWZ	3	4.00	8.00	3.30
WAFER-HY2.0-4PWZ	4	6.00	10.00	4.00
WAFER-HY2.0-5PWZ	5	8.00	12.00	6.00
WAFER-HY2.0-6PWZ	6	10.00	14.00	8.00
WAFER-HY2.0-7PWZ	7	12.00	16.00	10.00
WAFER-HY2.0-8PWZ	8	14.00	18.00	12.00
WAFER-HY2.0-9PWZ	9	16.00	20.00	14.00
WAFER-HY2.0-10PWZ	10	18.00	22.00	16.00
WAFER-HY2.0-11PWZ	11	20.00	24.00	18.00
WAFER-HY2.0-12PWZ	12	22.00	26.00	20.00
WAFER-HY2.0-13PWZ	13	24.00	28.00	22.00
WAFER-HY2.0-14PWZ	14	26.00	30.00	24.00
WAFER-HY2.0-15PWZ	15	28.00	32.00	26.00

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡80u"MIN
1	基座Wafer	PA66(UL94 V-0)	1	白色
序号	名称	材料	数量	备注
MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd		
UNLESS OTHERWISE SPECIFIED TOLERANCES				TITLE: WAFER HY2.0MM 弯针
DECIMALS:		ANGLES:		PAR
.X±0.20		±2'		WAFER-HY2.0-NPWZ
.XX±0.10				DWN
.XXX±0.05				CHKD
				APVD
				SCALE 1:1
				UNIT: MM
				SIZE: A4
				SHEET: 1F1
				REV: A